

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DB3J313K

Silicon epitaxial planar type

For small current rectification DB3X313K in SMini3 type package

■ Features

- Low forward voltage V_F and small reverse current I_R
- Low terminal capacitance C_t
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

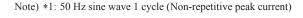
■ Marking Symbol: 4J

■ Packaging

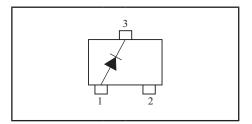
 $DB3J313K0L \quad Embossed \ type \ (Thermo-compression \ sealing): \ 3\,000 \ pcs \ / \ reel \ (standard)$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V _R	30	V	
Maximum peak reverse voltage	V _{RM}	30	V	
Forward current (Average)	I _{F(AV)}	200	mA	
Peak forward current	I_{FM}	300	mA	
Non-repetitive peak forward surge current *1	I _{FSM}	1	A	
Junction temperature	T _j	125	°C	
Operating ambient temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



Unit: mm 2. 0 0. 3 0. 13 (0. 65)(0. 65) 1. 3 1: Anode 2: N.C. 3: Cathode Panasonic Panasonic SMini3-F2-B JEITA SC-85 Code —

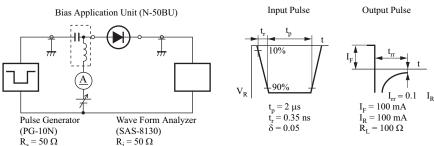


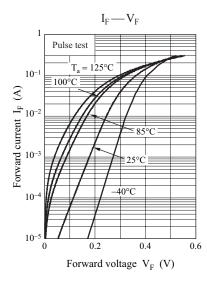
■ Electrical Characteristics $T_a = 25$ °C±3°C

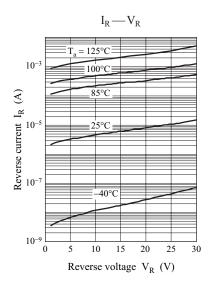
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F}	$I_F = 200 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			50	μΑ
Terminal capacitance	Ct	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		3.8		pF
Reverse recovery time *1	t _{rr}	$\begin{aligned} & I_F = I_R = 100 \text{ mA}, I_{rr} = 0.1 \times I_R, \\ & R_L = 100 \Omega \end{aligned}$		1.5		ns

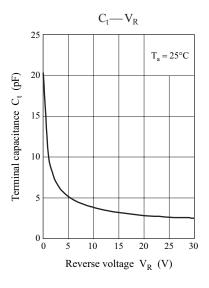
 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7031 \ measuring \ methods \ for \ diodes.$

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 1 GHz
 - *1: t_{rr} measurement circuit





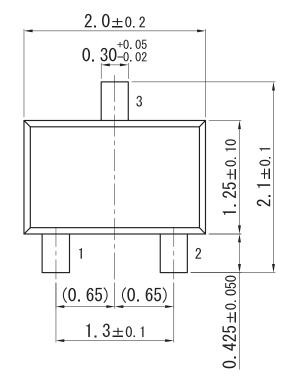


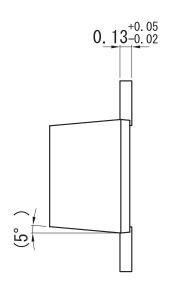


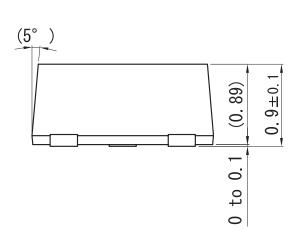
Ver. DED 2

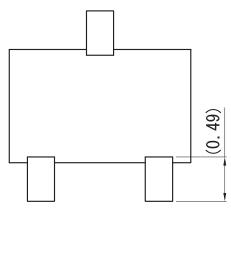
SMini3-F2-B

Unit: mm

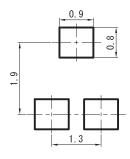








■ Land Pattern (Reference) (Unit: mm)



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